



高功率皮秒激光器

High Power Picosecond Fiber Laser

HP是一款混合固体放大皮秒激光器产品, 平均功率率30W, 其单脉冲能量以高达0.3mJ, 脉宽小于15ps, 由于单脉冲能量足够高从而能够满足高效加工蓝宝石、硅、陶瓷和玻璃等脆性衬底材料无论是切割还是打孔都能够满足。

HP laser is a high power picosecond laser, Max average power is 30W, the single pulse energy is up to 0.3 mJ, pulse width is less than 15 ps. This product is used to ceramic cutting, sapphire cutting, silicon cutting, and surface ink removing etc.

产品特点 Features

线偏振
Linear Polarization
优良的光束质量
Excellent Beam Quality
高抗反射能力
High Anti-reflection
免维护
Maintenance-free

产品应用 Applications

滤光片切割
Filter Cutting
陶瓷打孔切割
Drilling
蓝宝石切割
Sapphire Cutting
硅晶片加工
Wafer Scribing

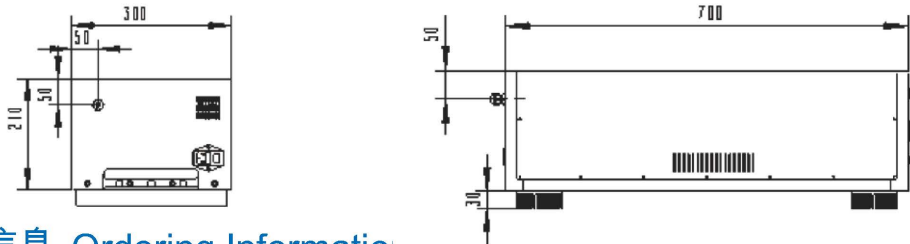


● 技术参数 Specifications

参数 Parameters	单位 Unit	Y12-HP
工作模式 (Working Mode)		脉冲 (Pulse)
中心波长 (Center Wavelength)	nm	1064±2
最大输出功率 (Max Optical Average Power)	W	30
典型输出功率 (Typical Output Power)	W	30w@100KHz
脉冲宽度 (Pulse Width)	ps	<15
输出脉冲个数 (Pulse Number)		1-8
重复频率 (Pulse Repetition Rate)	KHz	50-1000
偏振 (Polarization)		线偏 (linear)
消光比 (Extinction Ratio)	dB	> 20
最大脉冲能量 (Max Pulse Energy)	uJ	≤ 300
光束质量M2(Beam Quality M2)		≤1.2
输出光斑直径 (Collimated Beam Diameter)	mm	5.8±0.2
输出光功率可调范围 (Output Power Tunability)	%	0-100
功率稳定度 (Power Consumption)	%	<2
传递光纤长度 (Delivering Fiber Length)	m	1
工作环境 Working Conditions		
功率消耗 (Power Consumption)	W	<130
工作电压 (Electrical Supply Voltage)	VDC	24
工作温度 (Operating Temperature)	°C	20to30
存储温度 (Storage Temperature)	°C	0to50
体积 (Dimensions)(LxWxH)	mm	700x300x210
重量 (Weight)	kg	22

* 本产品可以根据客户要求定制
 Above specifications can be customized for your specific application.

● 机械结构 Mechanical Dimensions



● 订购信息 Ordering Information

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 Please contact with our sale staff.

www.gslasers.com